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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	Ethernet, I²C, IrDA, Microwire, SPI, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	70
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	A/D 8x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1767fbd100-551

3. Applications

- eMetering
- Lighting
- Industrial networking
- Alarm systems
- White goods
- Motor control

4. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
LPC1769FBD100	LQFP100	plastic low profile quad flat package; 100 leads; body 14 × 14 × 1.4 mm	SOT407-1
LPC1768FBD100	LQFP100	plastic low profile quad flat package; 100 leads; body 14 × 14 × 1.4 mm	SOT407-1
LPC1768FET100	TFBGA100	plastic thin fine-pitch ball grid array package; 100 balls; body 9 × 9 × 0.7 mm	SOT926-1
LPC1768UK	WLCSP100	wafer level chip-scale package; 100 balls; 5.07 × 5.07 × 0.53 mm	-
LPC1767FBD100	LQFP100	plastic low profile quad flat package; 100 leads; body 14 × 14 × 1.4 mm	SOT407-1
LPC1766FBD100	LQFP100	plastic low profile quad flat package; 100 leads; body 14 × 14 × 1.4 mm	SOT407-1
LPC1765FBD100	LQFP100	plastic low profile quad flat package; 100 leads; body 14 × 14 × 1.4 mm	SOT407-1
LPC1765FET100	TFBGA100	plastic thin fine-pitch ball grid array package; 100 balls; body 9 × 9 × 0.7 mm	SOT926-1
LPC1764FBD100	LQFP100	plastic low profile quad flat package; 100 leads; body 14 × 14 × 1.4 mm	SOT407-1
LPC1763FBD100	LQFP100	plastic low profile quad flat package; 100 leads; body 14 × 14 × 1.4 mm	SOT407-1

4.1 Ordering options

Table 2. Ordering options

Type number	Device order part number	Flash (kB)	SRAM in kB				Ethernet	USB	CAN	I^2S	DAC	GPIO	Maximum CPU operating frequency (MHz)
			CPU	AHB SRAM0	AHB SRAM1	Total							
LPC1769FBD100	LPC1769FBD100,551	512	32	16	16	64	yes	Device/Host/OTG	2	yes	yes	70	120
LPC1768FBD100	LPC1768FBD100/CP32	512	32	16	16	64	yes	Device/Host/OTG	2	yes	yes	70	100
LPC1768FET100	LPC1768FET100Z	512	32	16	16	64	yes	Device/Host/OTG	2	yes	yes	70	100
LPC1768UK	LPC1768UKZ	512	32	16	16	64	yes	Device/Host/OTG	2	yes	yes	70	100
LPC1767FBD100	LPC1767FBD100,551	512	32	16	16	64	yes	no	no	yes	yes	70	100
LPC1766FBD100	LPC1766FBD100,551	256	32	16	16	64	yes	Device/Host/OTG	2	yes	yes	70	100
LPC1765FBD100	LPC1765FBD100/3271	256	32	16	16	64	no	Device/Host/OTG	2	yes	yes	70	100
LPC1765FET100	LPC1765FET100,551	256	32	16	16	64	no	Device/Host/OTG	2	yes	yes	70	100
LPC1764FBD100	LPC1764FBD100,551	128	16	16	-	32	yes	Device only	2	no	no	70	100
LPC1763FBD100	LPC1763FBD100K	256	32	16	16	64	no	no	no	yes	yes	70	100

7. Pinning information

7.1 Pinning

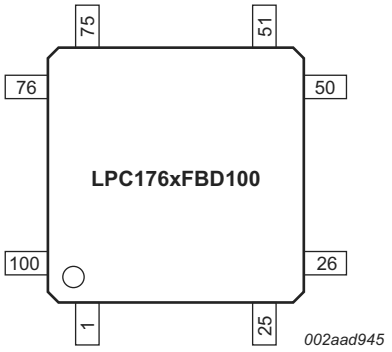


Fig 2. Pin configuration LQFP100 package

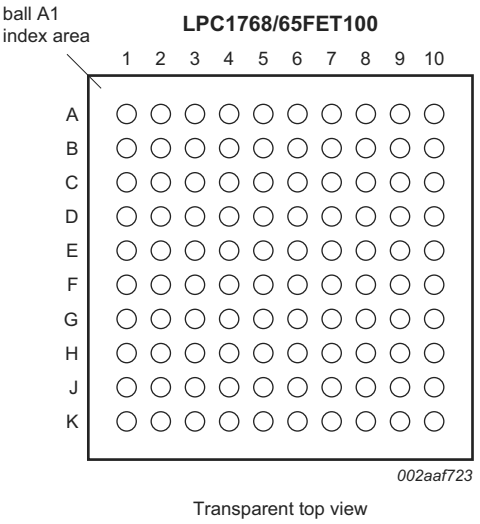


Fig 3. Pin configuration TFBGA100 package

Table 5. Pin description *…continued*

Symbol	Pin/ball				Type	Description
	LQFP100	TFBGA100	WLCSP100			
P1[25]/MCOA1/ MAT1[1]	39	G5	F9	[1]	I/O	**P1[25] —** General purpose digital input/output pin.
					O	**MCOA1 —** Motor control PWM channel 1, output A.
					O	**MAT1[1] —** Match output for Timer 1, channel 1.
P1[26]/MCOB1/ PWM1[6]/CAP0[0]	40	K6	E10	[1]	I/O	**P1[26] —** General purpose digital input/output pin.
					O	**MCOB1 —** Motor control PWM channel 1, output B.
					O	**PWM1[6] —** Pulse Width Modulator 1, channel 6 output.
					I	**CAP0[0] —** Capture input for Timer 0, channel 0.
P1[27]/CLKOUT /USB_OVRCR/ CAP0[1]	43	K7	G9	[1]	I/O	**P1[27] —** General purpose digital input/output pin.
					O	**CLKOUT —** Clock output pin.
					I	**USB_OVRCR —** USB port Over-Current status. (LPC1769/68/66/65 only).
					I	**CAP0[1] —** Capture input for Timer 0, channel 1.
P1[28]/MCOA2/ PCAP1[0]/ MAT0[0]	44	J7	G10	[1]	I/O	**P1[28] —** General purpose digital input/output pin.
					O	**MCOA2 —** Motor control PWM channel 2, output A.
					I	**PCAP1[0] —** Capture input for PWM1, channel 0.
					O	**MAT0[0] —** Match output for Timer 0, channel 0.
P1[29]/MCOB2/ PCAP1[1]/ MAT0[1]	45	G6	G8	[1]	I/O	**P1[29] —** General purpose digital input/output pin.
					O	**MCOB2 —** Motor control PWM channel 2, output B.
					I	**PCAP1[1] —** Capture input for PWM1, channel 1.
					O	**MAT0[1] —** Match output for Timer 0, channel 1.
P1[30]/V_{BUS}/ AD0[4]	21	H1	B8	[2]	I/O	**P1[30] —** General purpose digital input/output pin.
					I	**V_{BUS} —** Monitors the presence of USB bus power. (LPC1769/68/66/65/64 only). **Note:** This signal must be HIGH for USB reset to occur.
					I	**AD0[4] —** A/D converter 0, input 4.
P1[31]/SCK1/ AD0[5]	20	F4	C7	[2]	I/O	**P1[31] —** General purpose digital input/output pin.
					I/O	**SCK1 —** Serial Clock for SSP1.
					I	**AD0[5] —** A/D converter 0, input 5.
P2[0] to P2[31]					I/O	**Port 2:** Port 2 is a 32-bit I/O port with individual direction controls for each bit. The operation of port 2 pins depends upon the pin function selected via the pin connect block. Pins 14 through 31 of this port are not available.
P2[0]/PWM1[1]/ TXD1	75	B9	K1	[1]	I/O	**P2[0] —** General purpose digital input/output pin.
					O	**PWM1[1] —** Pulse Width Modulator 1, channel 1 output.
					O	**TXD1 —** Transmitter output for UART1.
P2[1]/PWM1[2]/ RXD1	74	B10	J2	[1]	I/O	**P2[1] —** General purpose digital input/output pin.
					O	**PWM1[2] —** Pulse Width Modulator 1, channel 2 output.
					I	**RXD1 —** Receiver input for UART1.

Table 5. Pin description *…continued*

Symbol	Pin/ball				Type	Description
	LQFP100	TFBGA100	WLCSP100			
P2[11]/$\overline{\text{EINT1}}$/ I2STX_CLK	52	H8	J8	[6]	I/O	**P2[11] —** General purpose digital input/output pin.
					I	**$\overline{\text{EINT1}}$ —** External interrupt 1 input.
					I/O	**I2STX_CLK —** Transmit Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the *I^2S-bus specification*. (LPC1769/68/67/66/65/63 only).
P2[12]/$\overline{\text{EINT2}}$/ I2STX_WS	51	K10	K10	[6]	I/O	**P2[12] —** General purpose digital input/output pin.
					I	**$\overline{\text{EINT2}}$ —** External interrupt 2 input.
					I/O	**I2STX_WS —** Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I^2S-bus specification*. (LPC1769/68/67/66/65/63 only).
P2[13]/$\overline{\text{EINT3}}$/ I2STX_SDA	50	J9	J9	[6]	I/O	**P2[13] —** General purpose digital input/output pin.
					I	**$\overline{\text{EINT3}}$ —** External interrupt 3 input.
					I/O	**I2STX_SDA —** Transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I^2S-bus specification*. (LPC1769/68/67/66/65/63 only).
P3[0] to P3[31]					I/O	**Port 3:** Port 3 is a 32-bit I/O port with individual direction controls for each bit. The operation of port 3 pins depends upon the pin function selected via the pin connect block. Pins 0 through 24, and 27 through 31 of this port are not available.
P3[25]/MAT0[0]/ PWM1[2]	27	H3	D8	[1]	I/O	**P3[25] —** General purpose digital input/output pin.
					O	**MAT0[0] —** Match output for Timer 0, channel 0.
					O	**PWM1[2] —** Pulse Width Modulator 1, output 2.
P3[26]/STCLK/ MAT0[1]/PWM1[3]	26	K1	A10	[1]	I/O	**P3[26] —** General purpose digital input/output pin.
					I	**STCLK —** System tick timer clock input. The maximum STCLK frequency is 1/4 of the Arm processor clock frequency CCLK.
					O	**MAT0[1] —** Match output for Timer 0, channel 1.
					O	**PWM1[3] —** Pulse Width Modulator 1, output 3.
P4[0] to P4[31]					I/O	**Port 4:** Port 4 is a 32-bit I/O port with individual direction controls for each bit. The operation of port 4 pins depends upon the pin function selected via the pin connect block. Pins 0 through 27, 30, and 31 of this port are not available.
P4[28]/RX_MCLK/ MAT2[0]/TXD3	82	C7	G1	[1]	I/O	**P4[28] —** General purpose digital input/output pin.
					O	**RX_MCLK —** I^2S receive master clock. (LPC1769/68/67/66/65 only).
					O	**MAT2[0] —** Match output for Timer 2, channel 0.
					O	**TXD3 —** Transmitter output for UART3.
P4[29]/TX_MCLK/ MAT2[1]/RXD3	85	E6	F1	[1]	I/O	**P4[29] —** General purpose digital input/output pin.
					O	**TX_MCLK —** I^2S transmit master clock. (LPC1769/68/67/66/65 only).
					O	**MAT2[1] —** Match output for Timer 2, channel 1.
					I	**RXD3 —** Receiver input for UART3.

Table 5. Pin description *…continued*

Symbol	Pin/ball				Type	Description
	LQFP100	TFBGA100	WLCSP100			
VREFN	15	F1	A6		I	**ADC negative reference voltage:** This should be nominally the same voltage as V_{SS} but should be isolated to minimize noise and error. Level on this pin is used as a reference for ADC and DAC.
VBAT	19	G2	A8	[10][12]	I	**RTC pin power supply:** 3.3 V on this pin supplies the power to the RTC peripheral.
n.c.	13	D4, E4	B6, D6		-	not connected.

[1] 5 V tolerant pad providing digital I/O functions with TTL levels and hysteresis. This pin is pulled up to a voltage level of 2.3 V to 2.6 V.

[2] 5 V tolerant pad providing digital I/O functions (with TTL levels and hysteresis) and analog input. When configured as a ADC input, digital section of the pad is disabled and the pin is not 5 V tolerant. This pin is pulled up to a voltage level of 2.3 V to 2.6 V.

[3] 5 V tolerant pad providing digital I/O with TTL levels and hysteresis and analog output function. When configured as the DAC output, digital section of the pad is disabled. This pin is pulled up to a voltage level of 2.3 V to 2.6 V.

[4] Open-drain 5 V tolerant digital I/O pad, compatible with I^2C-bus 400 kHz specification. This pad requires an external pull-up to provide output functionality. When power is switched off, this pin connected to the I^2C-bus is floating and does not disturb the I^2C lines. Open-drain configuration applies to all functions on this pin.

[5] Pad provides digital I/O and USB functions. It is designed in accordance with the *USB specification, revision 2.0* (Full-speed and Low-speed mode only). This pad is not 5 V tolerant.

[6] 5 V tolerant pad with 10 ns glitch filter providing digital I/O functions with TTL levels and hysteresis. This pin is pulled up to a voltage level of 2.3 V to 2.6 V.

[7] 5 V tolerant pad with TTL levels and hysteresis. Internal pull-up and pull-down resistors disabled.

[8] 5 V tolerant pad with TTL levels and hysteresis and internal pull-up resistor.

[9] 5 V tolerant pad with 20 ns glitch filter providing digital I/O function with TTL levels and hysteresis.

[10] Pad provides special analog functionality. A 32 kHz crystal oscillator must be used with the RTC.

[11] When the system oscillator is not used, connect XTAL1 and XTAL2 as follows: XTAL1 can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTAL2 should be left floating.

[12] When the RTC is not used, connect VBAT to $V_{DD(REG)(3V3)}$ and leave RTCX1 floating.

8.9.1 Features

- Eight DMA channels. Each channel can support an unidirectional transfer.
- 16 DMA request lines.
- Single DMA and burst DMA request signals. Each peripheral connected to the DMA Controller can assert either a burst DMA request or a single DMA request. The DMA burst size is set by programming the DMA Controller.
- Memory-to-memory, memory-to-peripheral, peripheral-to-memory, and peripheral-to-peripheral transfers are supported.
- Scatter or gather DMA is supported through the use of linked lists. This means that the source and destination areas do not have to occupy contiguous areas of memory.
- Hardware DMA channel priority.
- AHB slave DMA programming interface. The DMA Controller is programmed by writing to the DMA control registers over the AHB slave interface.
- One AHB bus master for transferring data. The interface transfers data when a DMA request goes active.
- 32-bit AHB master bus width.
- Incrementing or non-incrementing addressing for source and destination.
- Programmable DMA burst size. The DMA burst size can be programmed to more efficiently transfer data.
- Internal four-word FIFO per channel.
- Supports 8, 16, and 32-bit wide transactions.
- Big-endian and little-endian support. The DMA Controller defaults to little-endian mode on reset.
- An interrupt to the processor can be generated on a DMA completion or when a DMA error has occurred.
- Raw interrupt status. The DMA error and DMA count raw interrupt status can be read prior to masking.

8.10 Fast general purpose parallel I/O

Device pins that are not connected to a specific peripheral function are controlled by the GPIO registers. Pins may be dynamically configured as inputs or outputs. Separate registers allow setting or clearing any number of outputs simultaneously. The value of the output register may be read back as well as the current state of the port pins.

LPC17xx use accelerated GPIO functions:

- GPIO registers are accessed through the AHB multilayer bus so that the fastest possible I/O timing can be achieved.
- Mask registers allow treating sets of port bits as a group, leaving other bits unchanged.
- All GPIO registers are byte and half-word addressable.
- Entire port value can be written in one instruction.
- Support for Cortex-M3 bit banding.
- Support for use with the GPDMA controller.

- Up to four external outputs corresponding to match registers, with the following capabilities:
  - Set LOW on match.
  - Set HIGH on match.
  - Toggle on match.
  - Do nothing on match.
- Up to two match registers can be used to generate timed DMA requests.

8.22 Pulse width modulator

The PWM is based on the standard Timer block and inherits all of its features, although only the PWM function is pinned out on the LPC17xx. The Timer is designed to count cycles of the system derived clock and optionally switch pins, generate interrupts or perform other actions when specified timer values occur, based on seven match registers. The PWM function is in addition to these features, and is based on match register events.

The ability to separately control rising and falling edge locations allows the PWM to be used for more applications. For instance, multi-phase motor control typically requires three non-overlapping PWM outputs with individual control of all three pulse widths and positions.

Two match registers can be used to provide a single edge controlled PWM output. One match register (PWMMR0) controls the PWM cycle rate, by resetting the count upon match. The other match register controls the PWM edge position. Additional single edge controlled PWM outputs require only one match register each, since the repetition rate is the same for all PWM outputs. Multiple single edge controlled PWM outputs will all have a rising edge at the beginning of each PWM cycle, when an PWMMR0 match occurs.

Three match registers can be used to provide a PWM output with both edges controlled. Again, the PWMMR0 match register controls the PWM cycle rate. The other match registers control the two PWM edge positions. Additional double edge controlled PWM outputs require only two match registers each, since the repetition rate is the same for all PWM outputs.

With double edge controlled PWM outputs, specific match registers control the rising and falling edge of the output. This allows both positive going PWM pulses (when the rising edge occurs prior to the falling edge), and negative going PWM pulses (when the falling edge occurs prior to the rising edge).

8.22.1 Features

- One PWM block with Counter or Timer operation (may use the peripheral clock or one of the capture inputs as the clock source).
- Seven match registers allow up to 6 single edge controlled or 3 double edge controlled PWM outputs, or a mix of both types. The match registers also allow:
  - Continuous operation with optional interrupt generation on match.
  - Stop timer on match with optional interrupt generation.
  - Reset timer on match with optional interrupt generation.

See Figure 6 for an overview of the LPC17xx clock generation.

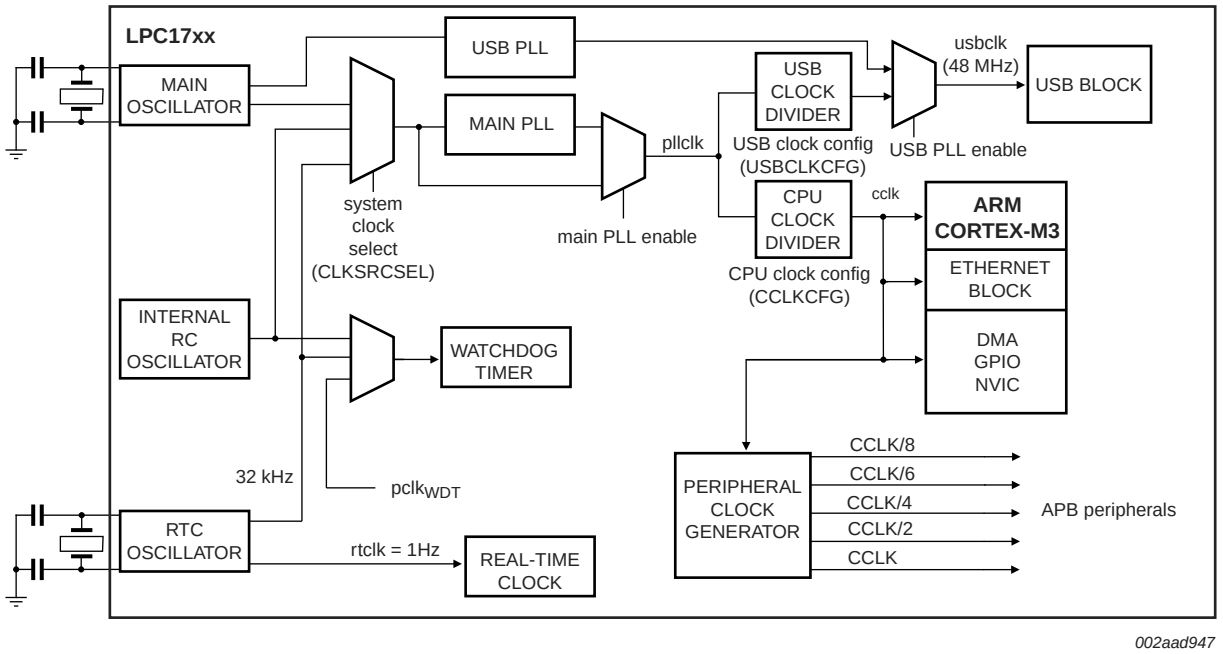


Fig 6. LPC17xx clocking generation block diagram

8.29.1.1 Internal RC oscillator

The IRC may be used as the clock source for the WDT, and/or as the clock that drives the PLL and subsequently the CPU. The nominal IRC frequency is 4 MHz. The IRC is trimmed to 1 % accuracy over the entire voltage and temperature range.

Upon power-up or any chip reset, the LPC17xx use the IRC as the clock source. Software may later switch to one of the other available clock sources.

8.29.1.2 Main oscillator

The main oscillator can be used as the clock source for the CPU, with or without using the PLL. The main oscillator also provides the clock source for the dedicated USB PLL.

The main oscillator operates at frequencies of 1 MHz to 25 MHz. This frequency can be boosted to a higher frequency, up to the maximum CPU operating frequency, by the main PLL. The clock selected as the PLL input is PLLCLKIN. The Arm processor clock frequency is referred to as CCLK elsewhere in this document. The frequencies of PLLCLKIN and CCLK are the same value unless the PLL is active and connected. The clock frequency for each peripheral can be selected individually and is referred to as PCLK. Refer to Section 8.29.2 for additional information.

8.29.1.3 RTC oscillator

The RTC oscillator can be used as the clock source for the RTC block, the main PLL, and/or the CPU.

The Deep-sleep mode can be terminated and normal operation resumed by either a Reset or certain specific interrupts that are able to function without clocks. Since all dynamic operation of the chip is suspended, Deep-sleep mode reduces chip power consumption to a very low value. Power to the flash memory is left on in Deep-sleep mode, allowing a very quick wake-up.

On wake-up from Deep-sleep mode, the code execution and peripherals activities will resume after 4 cycles expire if the IRC was used before entering Deep-sleep mode. If the main external oscillator was used, the code execution will resume when 4096 cycles expire. PLL and clock dividers need to be reconfigured accordingly.

8.29.6.3 Power-down mode

Power-down mode does everything that Deep-sleep mode does, but also turns off the power to the IRC oscillator and the flash memory. This saves more power but requires waiting for resumption of flash operation before execution of code or data access in the flash memory can be accomplished.

On the wake-up of Power-down mode, if the IRC was used before entering Power-down mode, it will take IRC 60 μs to start-up. After this 4 IRC cycles will expire before the code execution can then be resumed if the code was running from SRAM. In the meantime, the flash wake-up timer then counts 4 MHz IRC clock cycles to make the 100 μs flash start-up time. When it times out, access to the flash will be allowed. Users need to reconfigure the PLL and clock dividers accordingly.

8.29.6.4 Deep power-down mode

The Deep power-down mode can only be entered from the RTC block. In Deep power-down mode, power is shut off to the entire chip with the exception of the RTC module and the $\overline{\text{RESET}}$ pin.

The LPC17xx can wake up from Deep power-down mode via the $\overline{\text{RESET}}$ pin or an alarm match event of the RTC.

8.29.6.5 Wake-up interrupt controller

The Wake-up Interrupt Controller (WIC) allows the CPU to automatically wake up from any enabled priority interrupt that can occur while the clocks are stopped in Deep sleep, Power-down, and Deep power-down modes.

The WIC works in connection with the Nested Vectored Interrupt Controller (NVIC). When the CPU enters Deep sleep, Power-down, or Deep power-down mode, the NVIC sends a mask of the current interrupt situation to the WIC.This mask includes all of the interrupts that are both enabled and of sufficient priority to be serviced immediately. With this information, the WIC simply notices when one of the interrupts has occurred and then it wakes up the CPU.

The WIC eliminates the need to periodically wake up the CPU and poll the interrupts resulting in additional power savings.

8.29.7 Peripheral power control

A Power Control for Peripherals feature allows individual peripherals to be turned off if they are not needed in the application, resulting in additional power savings.

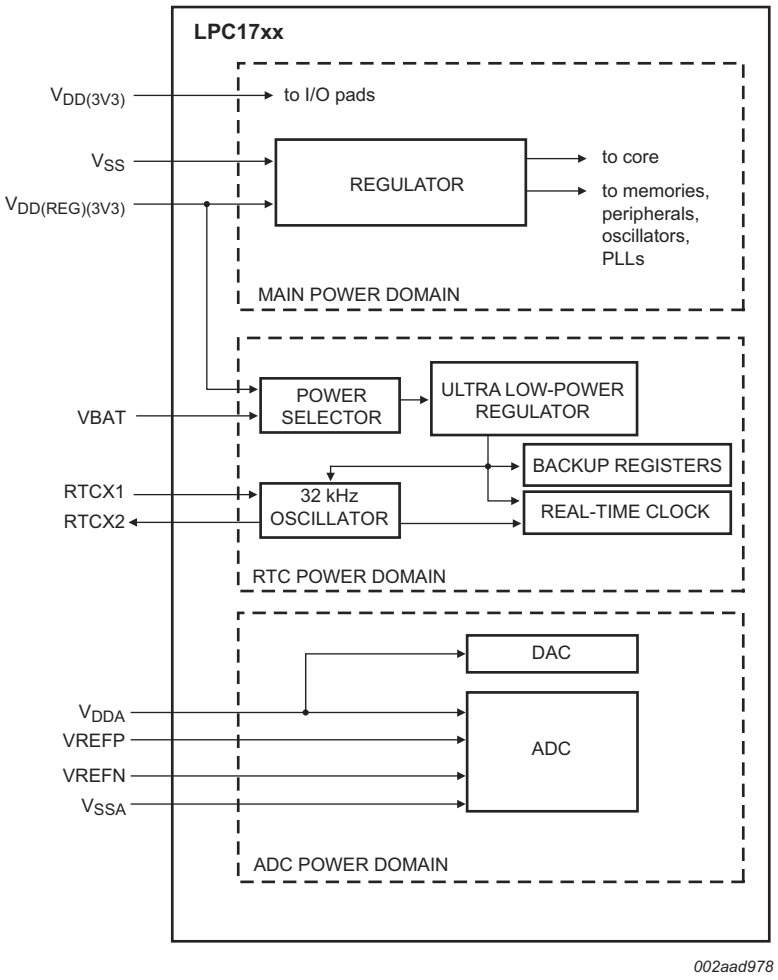


Fig 7. Power distribution

8.30 System control

8.30.1 Reset

Reset has four sources on the LPC17xx: the $\overline{\text{RESET}}$ pin, the Watchdog reset, power-on reset (POR), and the BrownOut Detection (BOD) circuit. The $\overline{\text{RESET}}$ pin is a Schmitt trigger input pin. Assertion of chip Reset by any source, once the operating voltage attains a usable level, causes the $\overline{\text{RSTOUT}}$ pin to go LOW and starts the wake-up timer (see description in Section 8.29.5). The wake-up timer ensures that reset remains asserted until the external Reset is de-asserted, the oscillator is running, a fixed number of clocks have passed, and the flash controller has completed its initialization. Once reset is de-asserted, or, in case of a BOD-triggered reset, once the voltage rises above the BOD threshold, the $\overline{\text{RSTOUT}}$ pin goes HIGH.

When the internal Reset is removed, the processor begins executing at address 0, which is initially the Reset vector mapped from the Boot Block. At that point, all of the processor and peripheral registers have been initialized to predetermined values.

[5] The RTC typically fails when $V_{i(VBAT)}$ drops below 1.6 V.

[6] $V_{DD(REG)(3V3)}$ = 3.3 V; T_{amb} = 25 °C for all power consumption measurements.

[7] Applies to LPC1768/67/66/65/64/63.

[8] Applies to LPC1769 only.

[9] IRC running at 4 MHz; main oscillator and PLL disabled; PCLK = $^{CCLK}/_{8}$.

[10] BOD disabled.

[11] On pin $V_{DD(REG)(3V3)}$. I_{BAT} = 530 nA. $V_{DD(REG)(3V3)}$ = 3.0 V; V_{BAT} = 3.0 V; T_{amb} = 25 °C.

[12] On pin VBAT; $I_{DD(REG)(3V3)}$ = 630 nA; $V_{DD(REG)(3V3)}$ = 3.0 V; V_{BAT} = 3.0 V; T_{amb} = 25 °C.

[13] On pin VBAT; V_{BAT} = 3.0 V; T_{amb} = 25 °C.

[14] All internal pull-ups disabled. All pins configured as output and driven LOW. $V_{DD(3V3)}$ = 3.3 V; T_{amb} = 25 °C.

[15] TCK/SWDCLK pin needs to be externally pulled LOW.

[16] On pin V_{DDA}; V_{DDA} = 3.3 V; T_{amb} = 25 °C. The ADC is powered if the PDN bit in the AD0CR register is set to 1 and in Power-down mode of the PDN bit is set to 0.

[17] The ADC is powered if the PDN bit in the AD0CR register is set to 1. See *LPC17xx user manual UM10360_1*.

[18] The ADC is in Power-down mode if the PDN bit in the AD0CR register is set to 0. See *LPC17xx user manual UM10360_1*.

[19] $V_{i(VREFP)}$ = 3.3 V; T_{amb} = 25 °C.

[20] Including voltage on outputs in 3-state mode.

[21] $V_{DD(3V3)}$ supply voltages must be present.

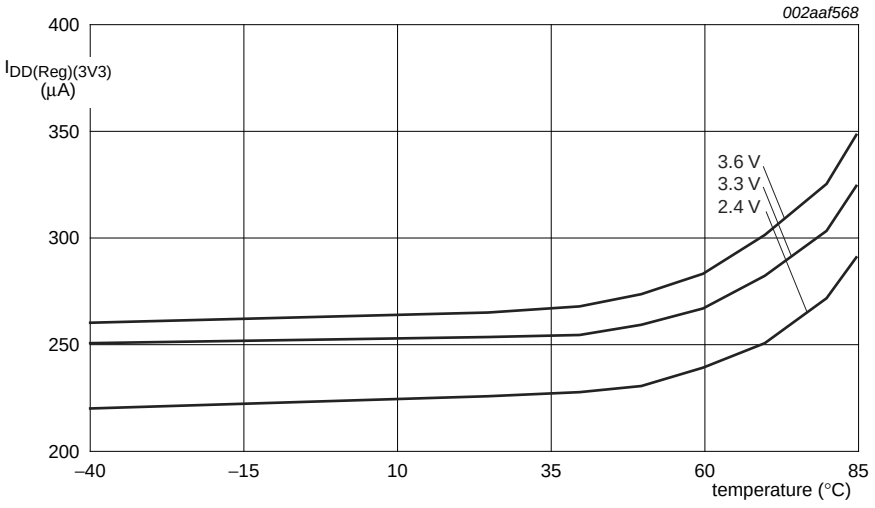
[22] 3-state outputs go into 3-state mode in Deep power-down mode.

[23] Allowed as long as the current limit does not exceed the maximum current allowed by the device.

[24] To V_{SS}.

[25] Includes external resistors of 33 Ω ± 1 % on D+ and D−.

11.1 Power consumption



Conditions: BOD disabled.

Fig 8. Deep-sleep mode: typical regulator supply current $I_{DD(Reg)(3V3)}$ versus temperature

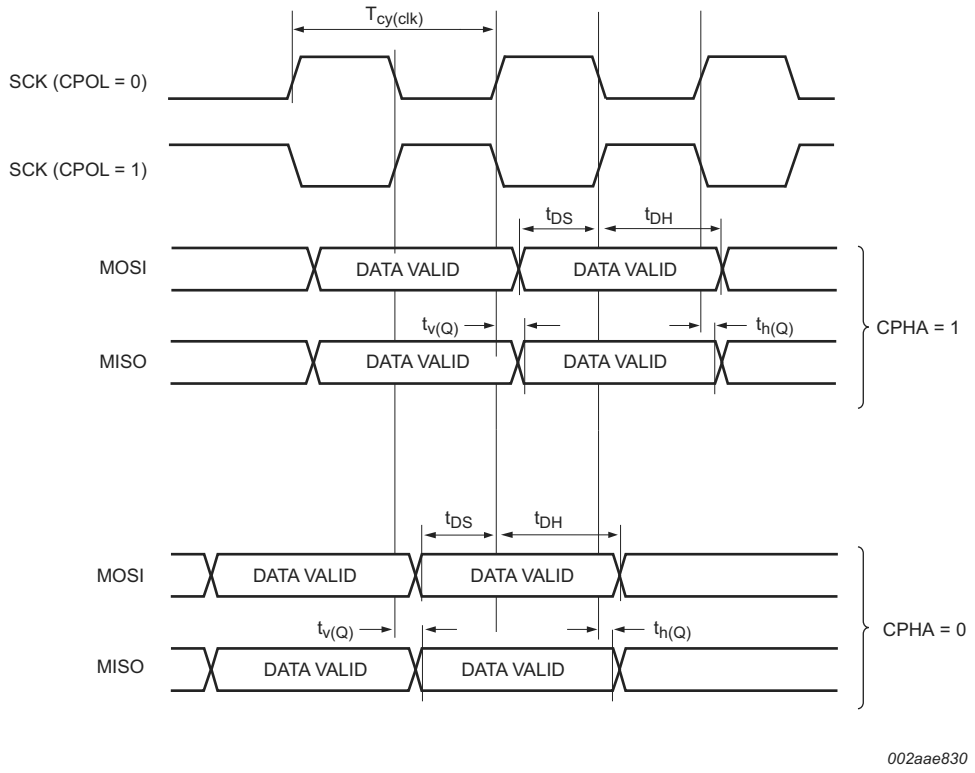


Fig 22. SSP slave timing in SPI mode

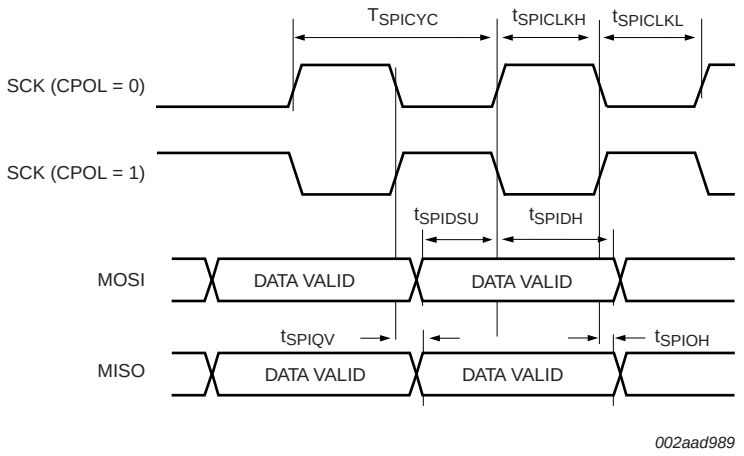


Fig 27. SPI slave timing (CPHA = 0)

13. ADC electrical characteristics

Table 19. ADC characteristics (full resolution)

V_{DDA} = 2.5 V to 3.6 V; T_{amb} = −40 °C to +85 °C unless otherwise specified; ADC frequency 13 MHz; 12-bit resolution.[1]

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IA}	analog input voltage			0	-	V_{DDA}	V
C_{ia}	analog input capacitance			-	-	15	pF
E_D	differential linearity error		[2][3]	-	-	±1	LSB
$E_{L(adj)}$	integral non-linearity		[4]	-	-	±3	LSB
E_O	offset error		[5][6]	-	-	±2	LSB
E_G	gain error		[7]	-	-	0.5	%
E_T	absolute error		[8]	-	-	4	LSB
R_{vsi}	voltage source interface resistance		[9]	-	-	7.5	kΩ
$f_{clk(ADC)}$	ADC clock frequency			-	-	13	MHz
$f_{c(ADC)}$	ADC conversion frequency		[10]	-	-	200	kHz

[1] V_{DDA} and VREFP should be tied to $V_{DD(3V3)}$ if the ADC and DAC are not used.

[2] The ADC is monotonic, there are no missing codes.

[3] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See Figure 28.

[4] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See Figure 28.

[5] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See Figure 28.

[6] ADCOFFS value (bits 7:4) = 2 in the ADTRM register. See *LPC17xx user manual UM10360*.

[7] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See Figure 28.

[8] The absolute error (E_T) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve. See Figure 28.

[9] See Figure 29.

[10] The conversion frequency corresponds to the number of samples per second.

Table 20. ADC characteristics (lower resolution)

T_{amb} = −40 °C to +85 °C unless otherwise specified; 12-bit ADC used as 10-bit resolution ADC.[1]

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
E_D	differential linearity error		[2][3]	-	±1	-	LSB
$E_{L(adj)}$	integral non-linearity		[4]	-	±1.5	-	LSB
E_O	offset error		[5]	-	±2	-	LSB
E_G	gain error		[6]	-	±2	-	LSB
$f_{clk(ADC)}$	ADC clock frequency	$3.0\ V \leq V_{DDA} \leq 3.6\ V$		-	-	33	MHz
		$2.7\ V \leq V_{DDA} < 3.0\ V$		-	-	25	MHz
$f_{c(ADC)}$	ADC conversion frequency	$3\ V \leq V_{DDA} \leq 3.6\ V$	[7]	-	-	500	kHz
		$2.7\ V \leq V_{DDA} < 3.0\ V$	[7]	-	-	400	kHz

[1] V_{DDA} and VREFP should be tied to $V_{DD(3V3)}$ if the ADC and DAC are not used.

[2] The ADC is monotonic, there are no missing codes.

[3] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See Figure 28.

[4] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See Figure 28.

[5] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See Figure 28.

[6] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See Figure 28.

[7] The conversion frequency corresponds to the number of samples per second.

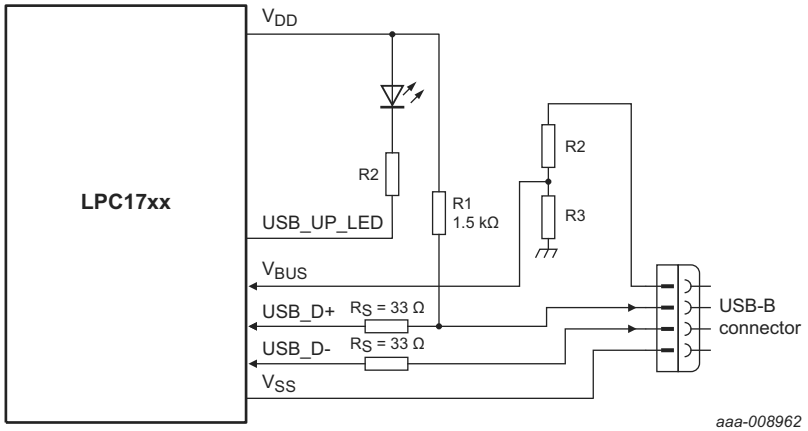


Fig 31. USB interface on a bus-powered device where V_{BUS} = 5 V, V_{DD} not present

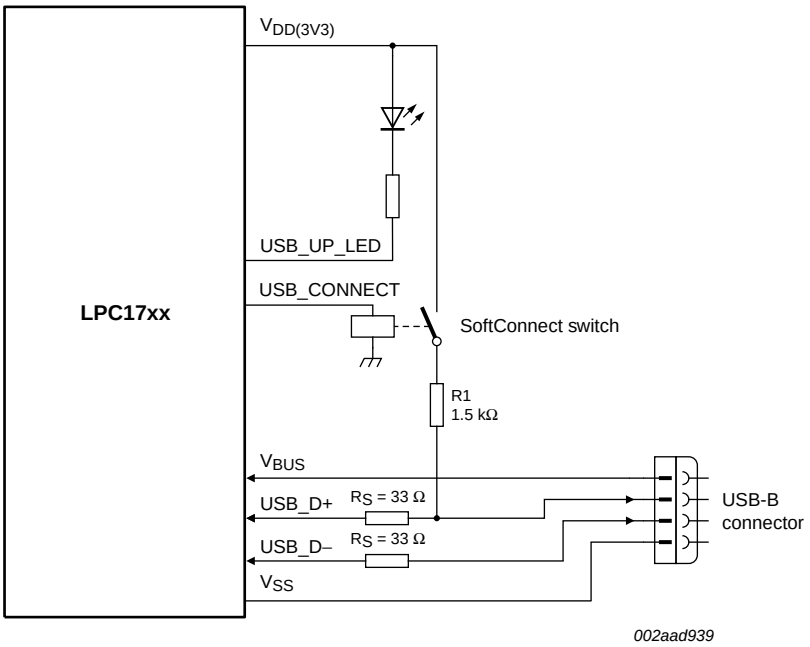


Fig 32. USB interface with soft-connect

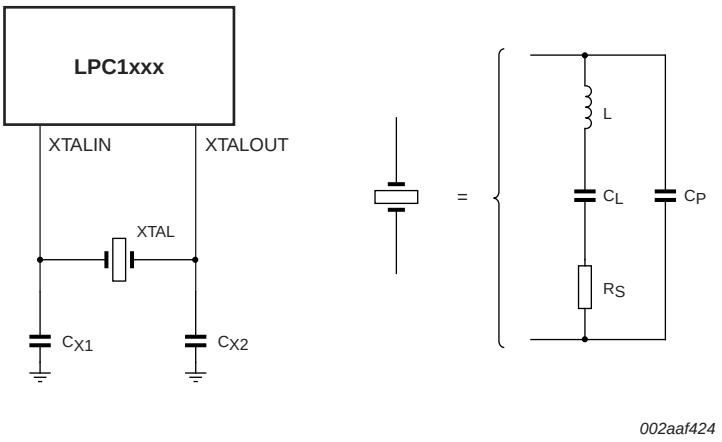


Fig 37. Oscillator modes and models: oscillation mode of operation and external crystal model used for C_{X1}/C_{X2} evaluation

Table 23. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters): low frequency mode

Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}/C_{X2}
1 MHz to 5 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 300 Ω	39 pF, 39 pF
	30 pF	< 300 Ω	57 pF, 57 pF
5 MHz to 10 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 200 Ω	39 pF, 39 pF
	30 pF	< 100 Ω	57 pF, 57 pF
10 MHz to 15 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 60 Ω	39 pF, 39 pF
15 MHz to 20 MHz	10 pF	< 80 Ω	18 pF, 18 pF

Table 24. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters): high frequency mode

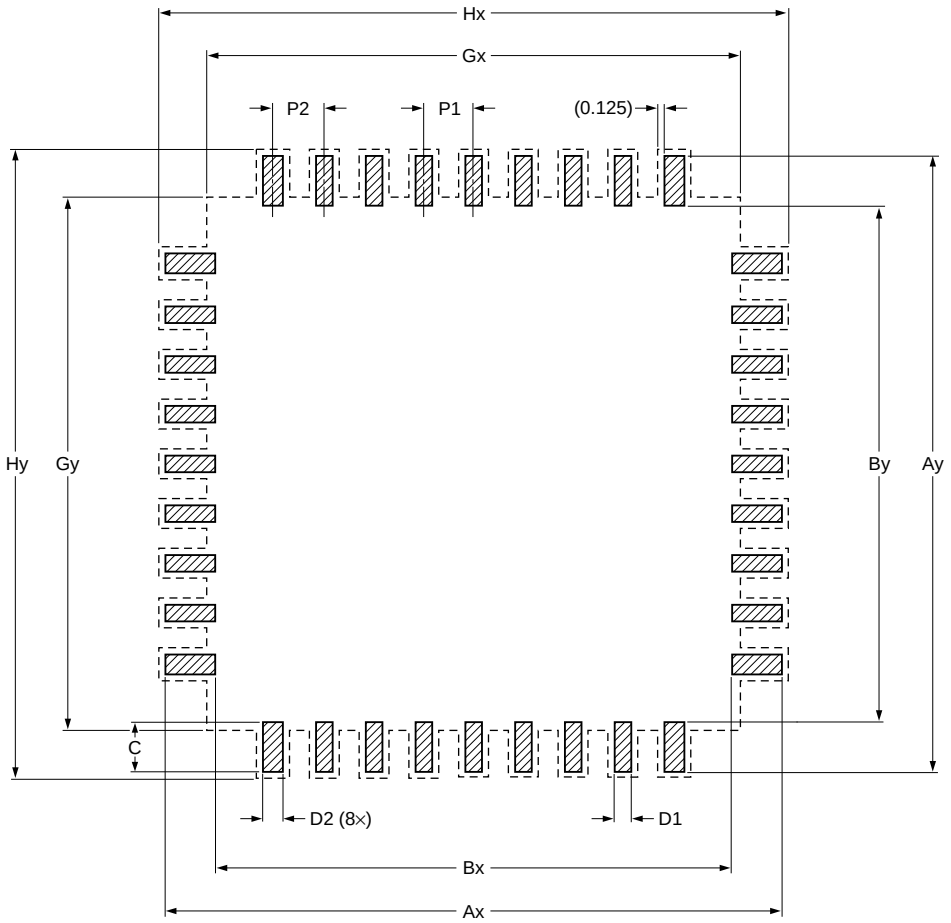
Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
15 MHz to 20 MHz	10 pF	< 180 Ω	18 pF, 18 pF
	20 pF	< 100 Ω	39 pF, 39 pF
20 MHz to 25 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 80 Ω	39 pF, 39 pF

15.3 XTAL and RTCX Printed Circuit Board (PCB) layout guidelines

The crystal should be connected on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors C_{x1}, C_{x2}, and C_{x3} in case of third overtone crystal usage have a common ground plane. The external components must also be connected to the ground plain. Loops must be made as small as possible in

17. Soldering

Footprint information for reflow soldering of LQFP100 package **SOT407-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

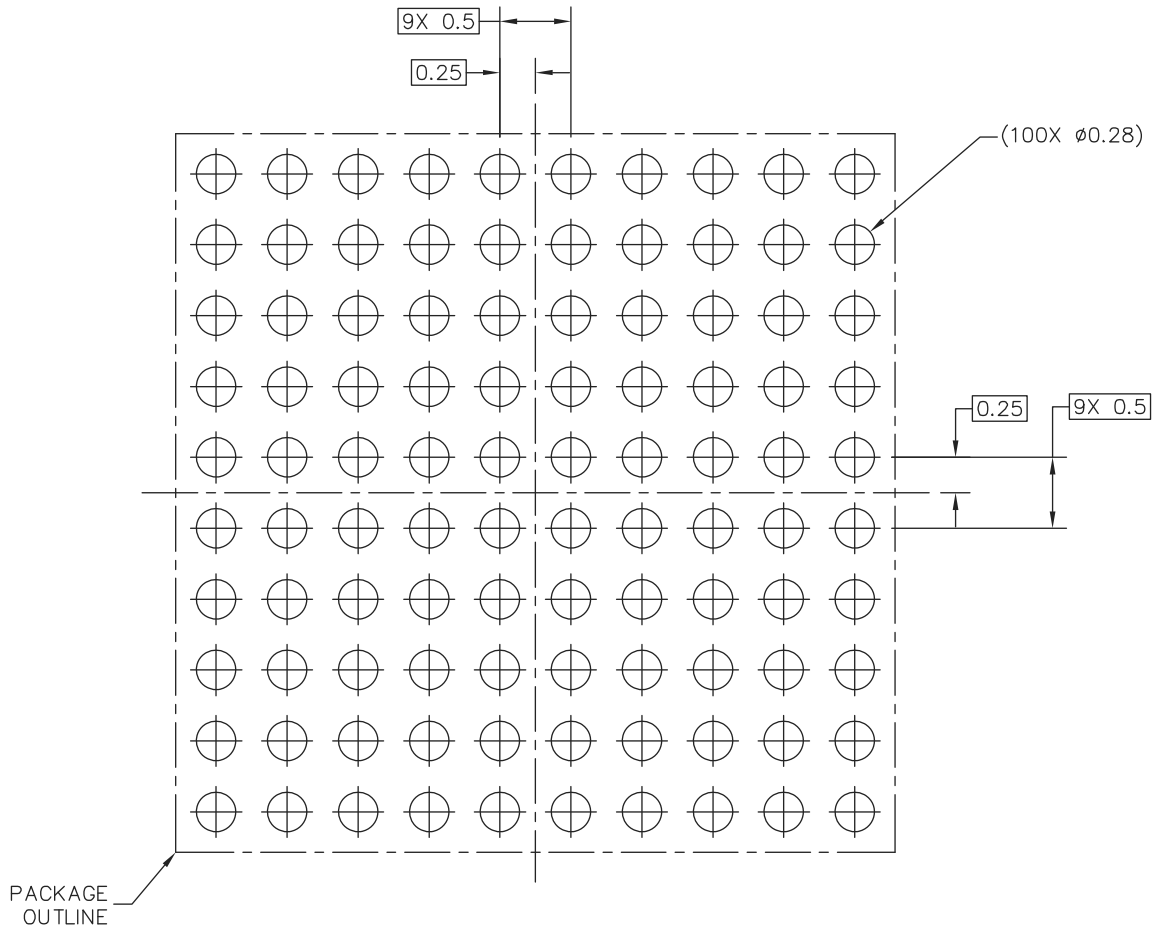
occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	17.300	17.300	14.300	14.300	1.500	0.280	0.400	14.500	14.500	17.550	17.550

sot407-1

Fig 43. Reflow soldering for the LQFP100 package



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

 DATE: 06 MAR 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1450-2	REVISION: 0	

Fig 46. Reflow soldering of the WLCSP100 package (part 2)

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